

ECR	ECR NUMBER	DATE
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SCHEMATIC SHEET INDEX:

- SHEET 01: TLK10022 HD-SDI REFERENCE DESIGN COVER SHEET AND NOTES
- SHEET 02: 1P0V REGULATORS
- SHEET 03: 1P5V, 1P8V, 2P5V, 3P3V REGULATORS
- SHEET 04: POWER DISTRIBUTION
- SHEET 05: VOLTAGE MONITORING
- SHEET 06: DEVICE POWER AND GROUND
- SHEET 07: GLOBAL SIGNALS
- SHEET 08: MDIO, JTAG, AND I2C INTERFACE
- SHEET 09: CLOCKS
- SHEET 10: CLOCK CONTROL
- SHEET 11: CRYSTAL OSCILLATORS
- SHEET 12: LOW SPEED DATA SIGNALS
- SHEET 13: HIGH SPEED DATA SIGNALS
- SHEET 14: DATA BOARD TO BOARD CONNECTOR
- SHEET 15: CLOCK BOARD TO BOARD CONNECTOR



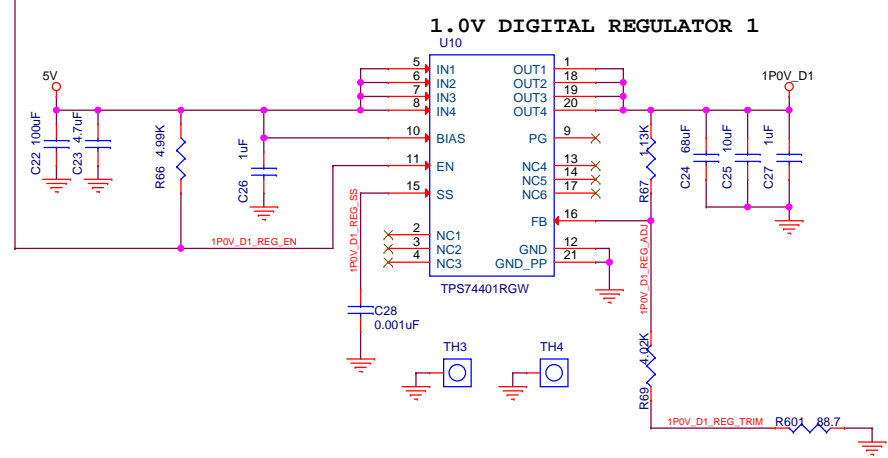
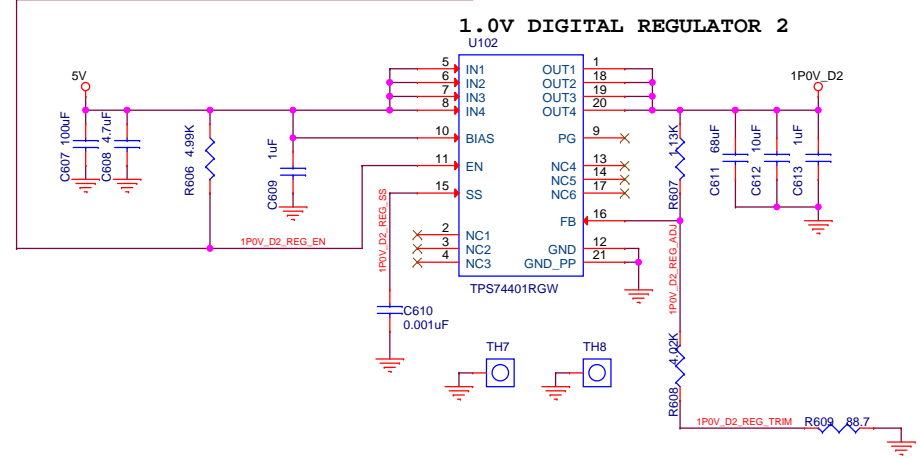
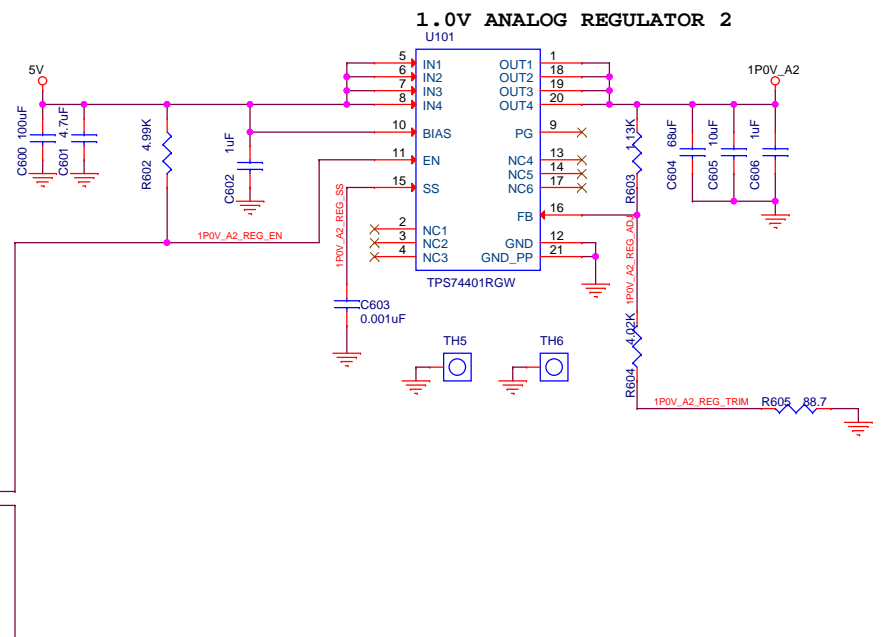
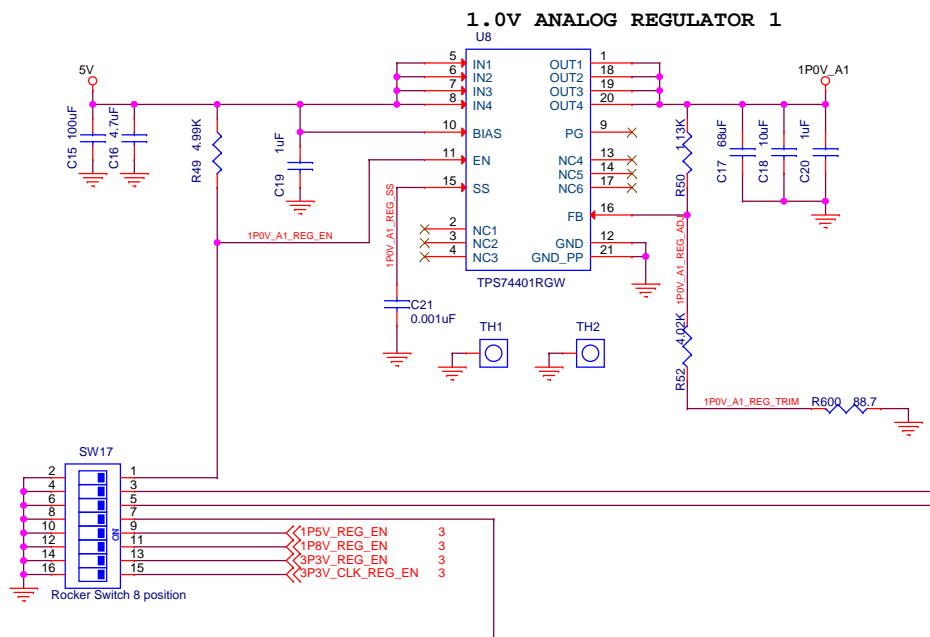
TEXAS INSTRUMENTS

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TIDA-00352
TLK10022 HD-SDI MOTHER BOARD

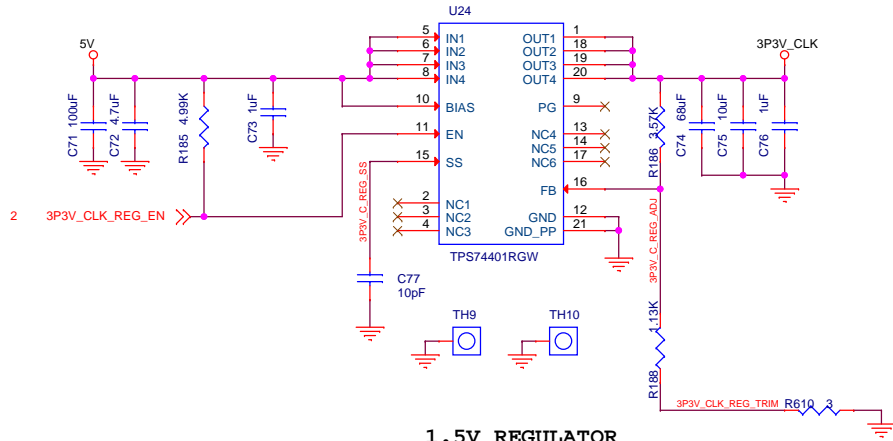
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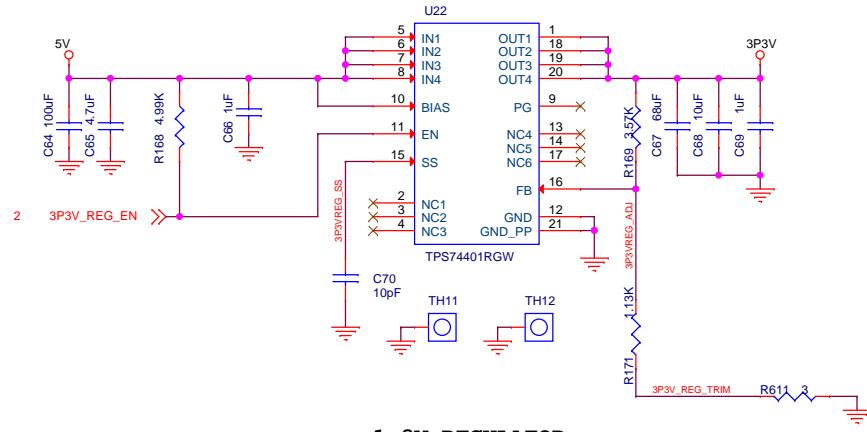
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B	6566789	B	1 of 15



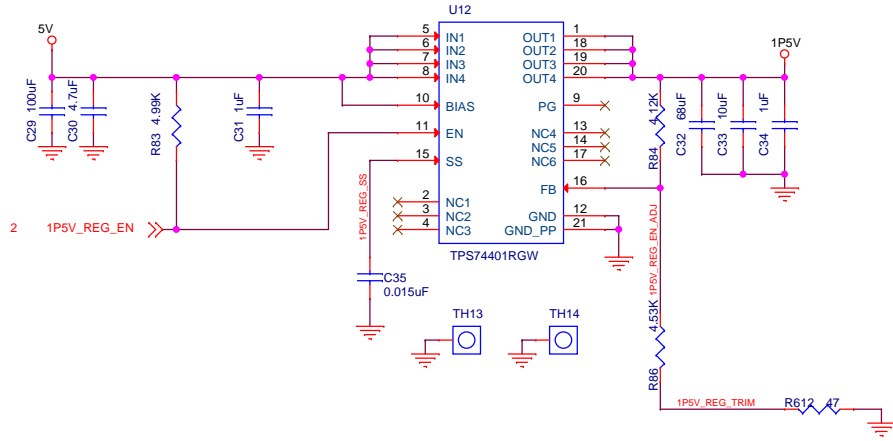
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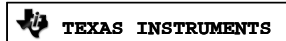
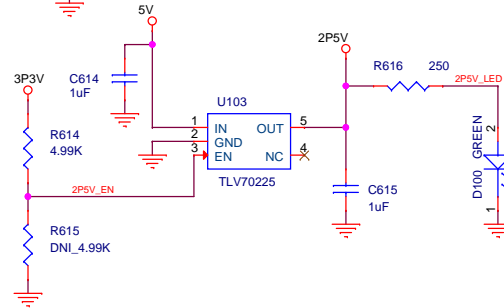
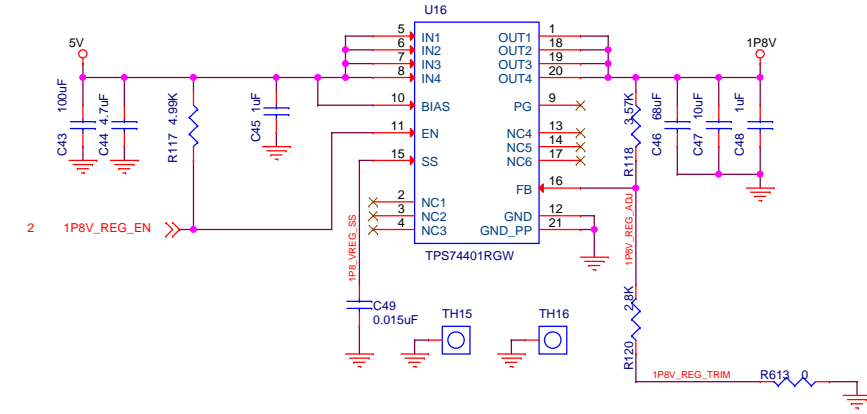
3.3V REGULATOR



1.5V REGULATOR

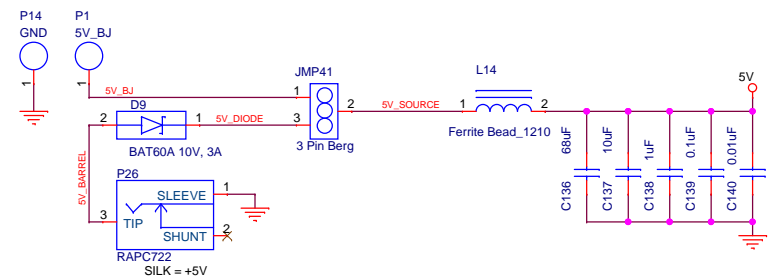
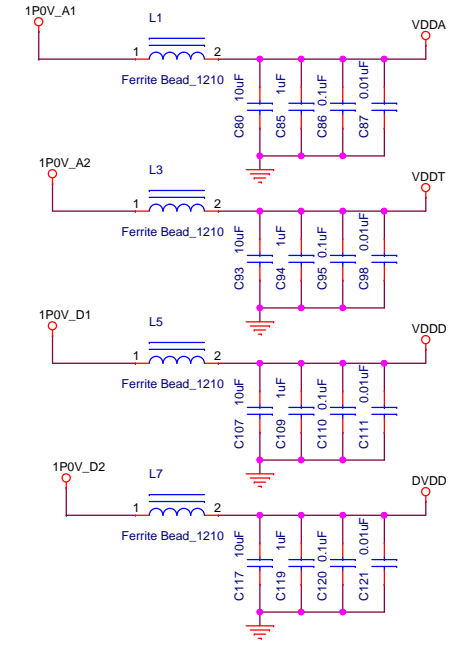
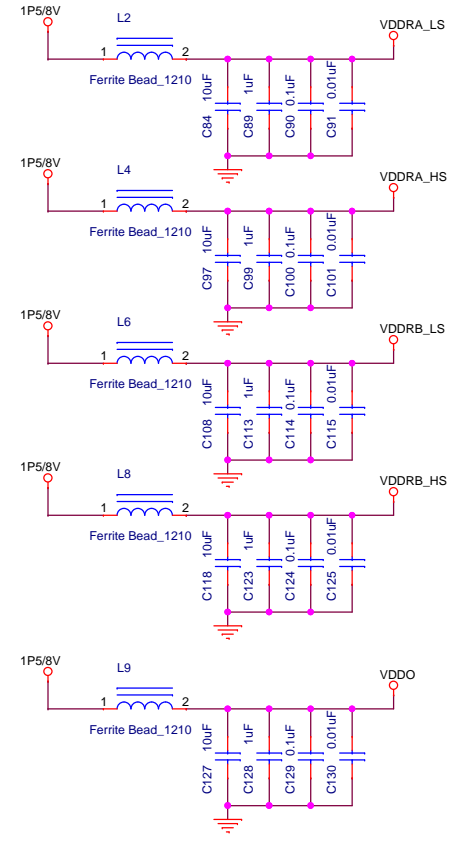
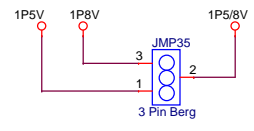
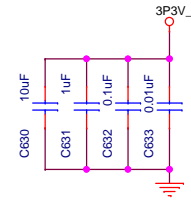
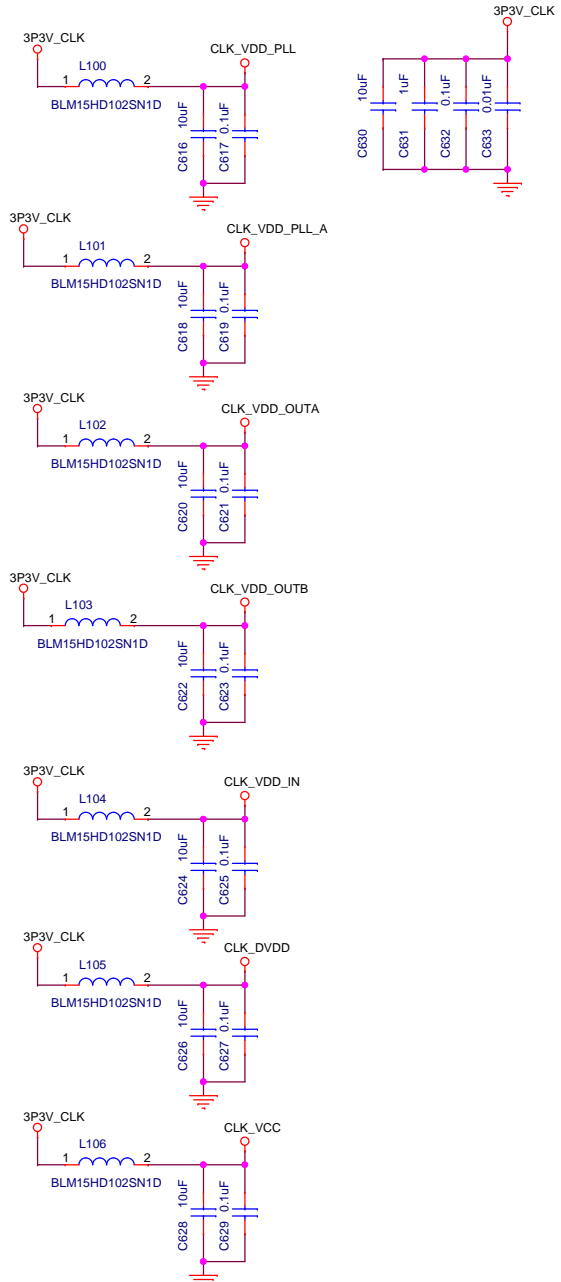


1.8V REGULATOR



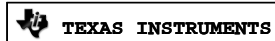
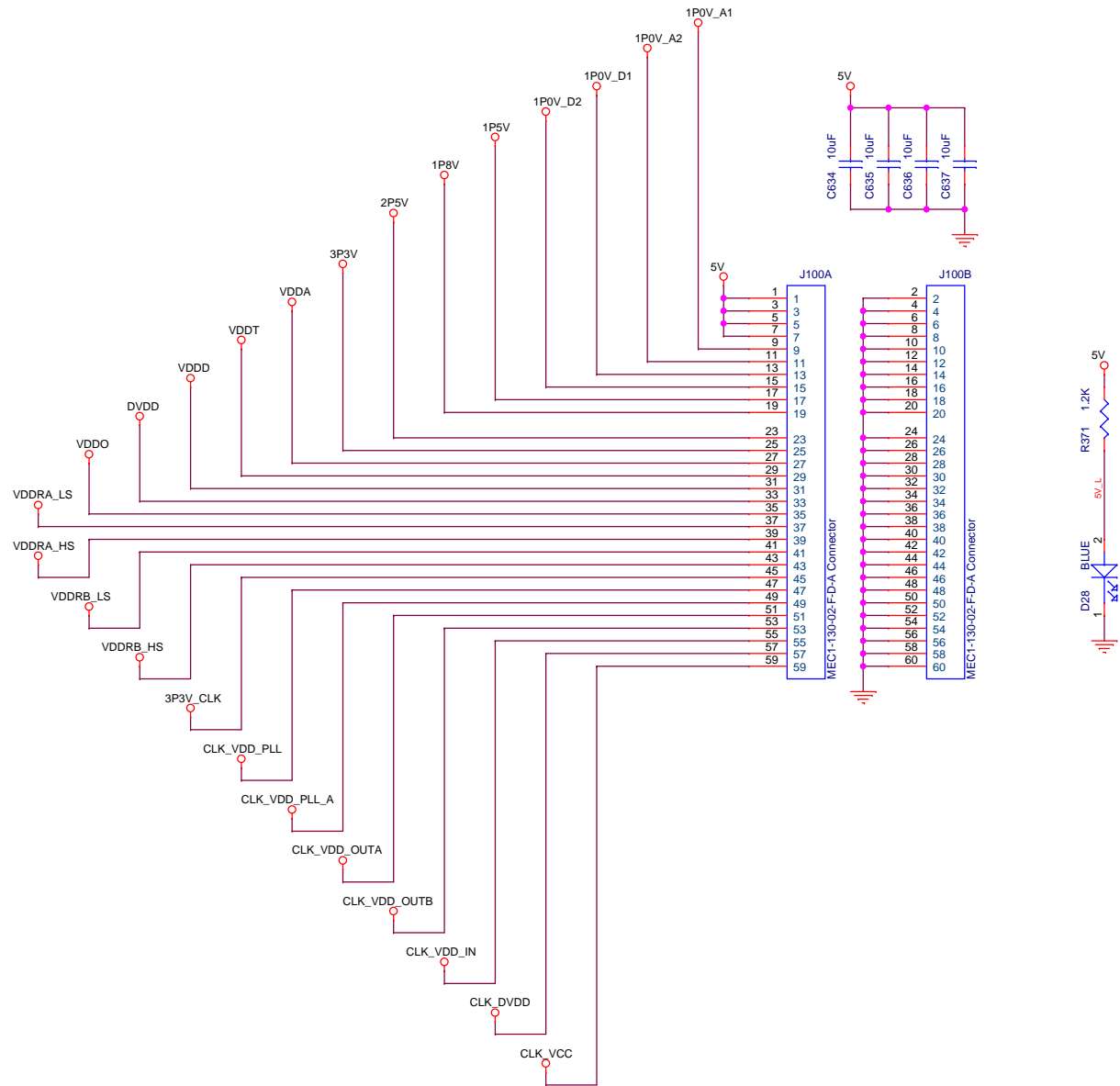
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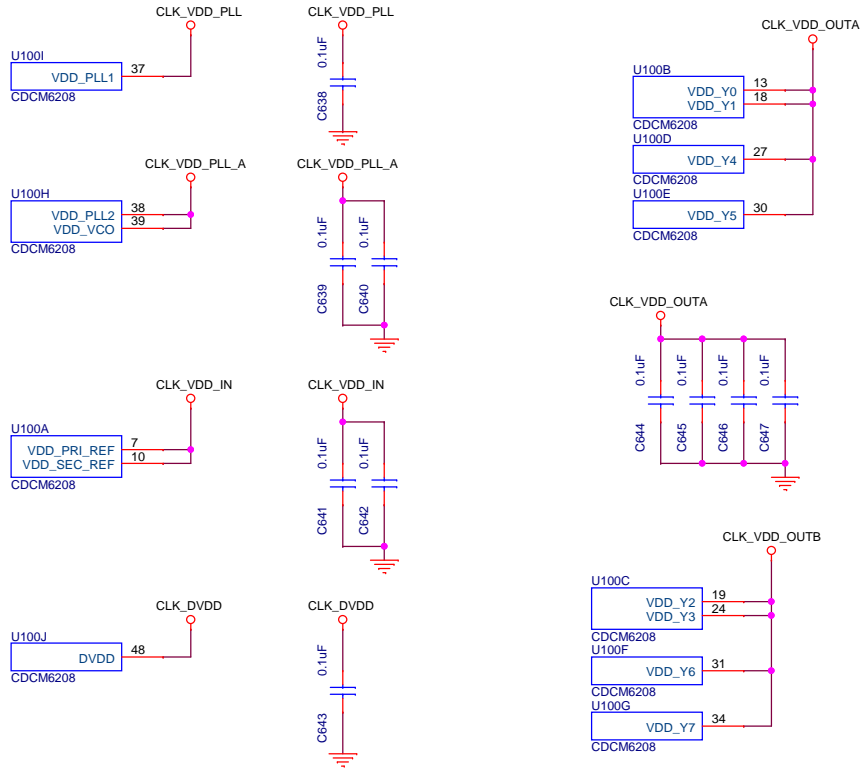


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B	6566789	B	4 of 15

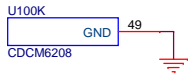
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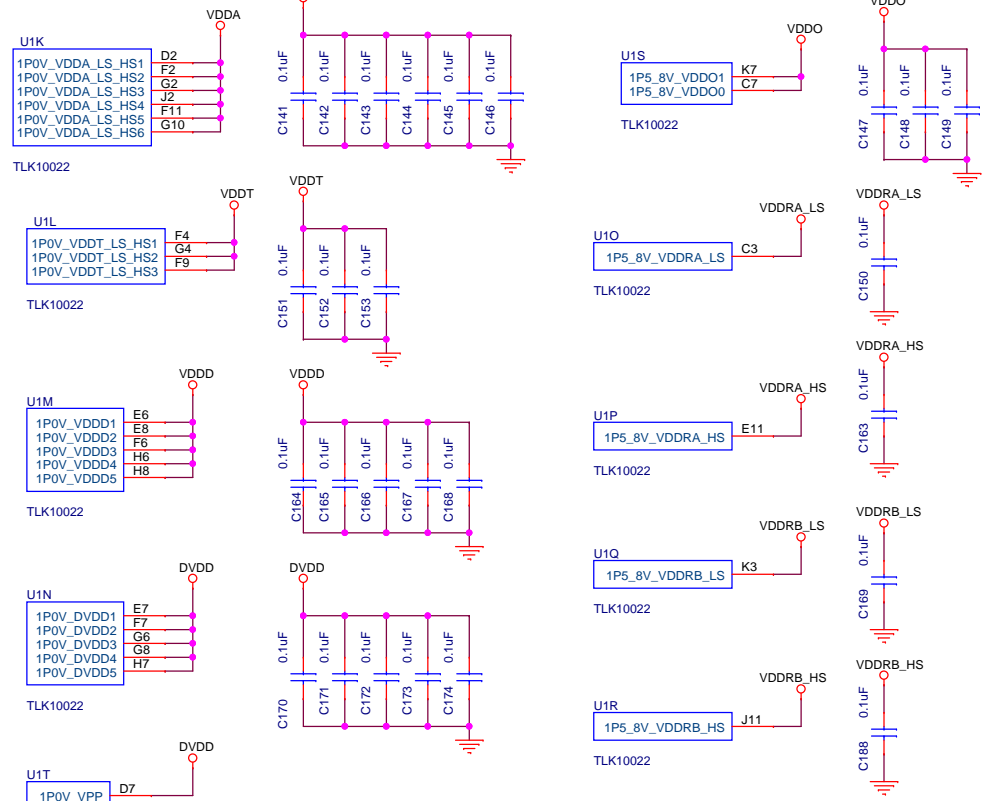
CDCM6208 DEVICE POWER / LOCAL DECOUPLING



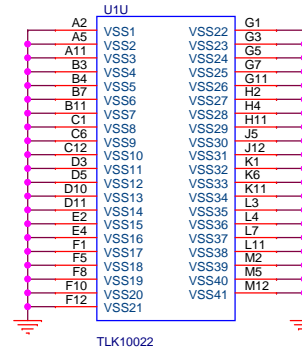
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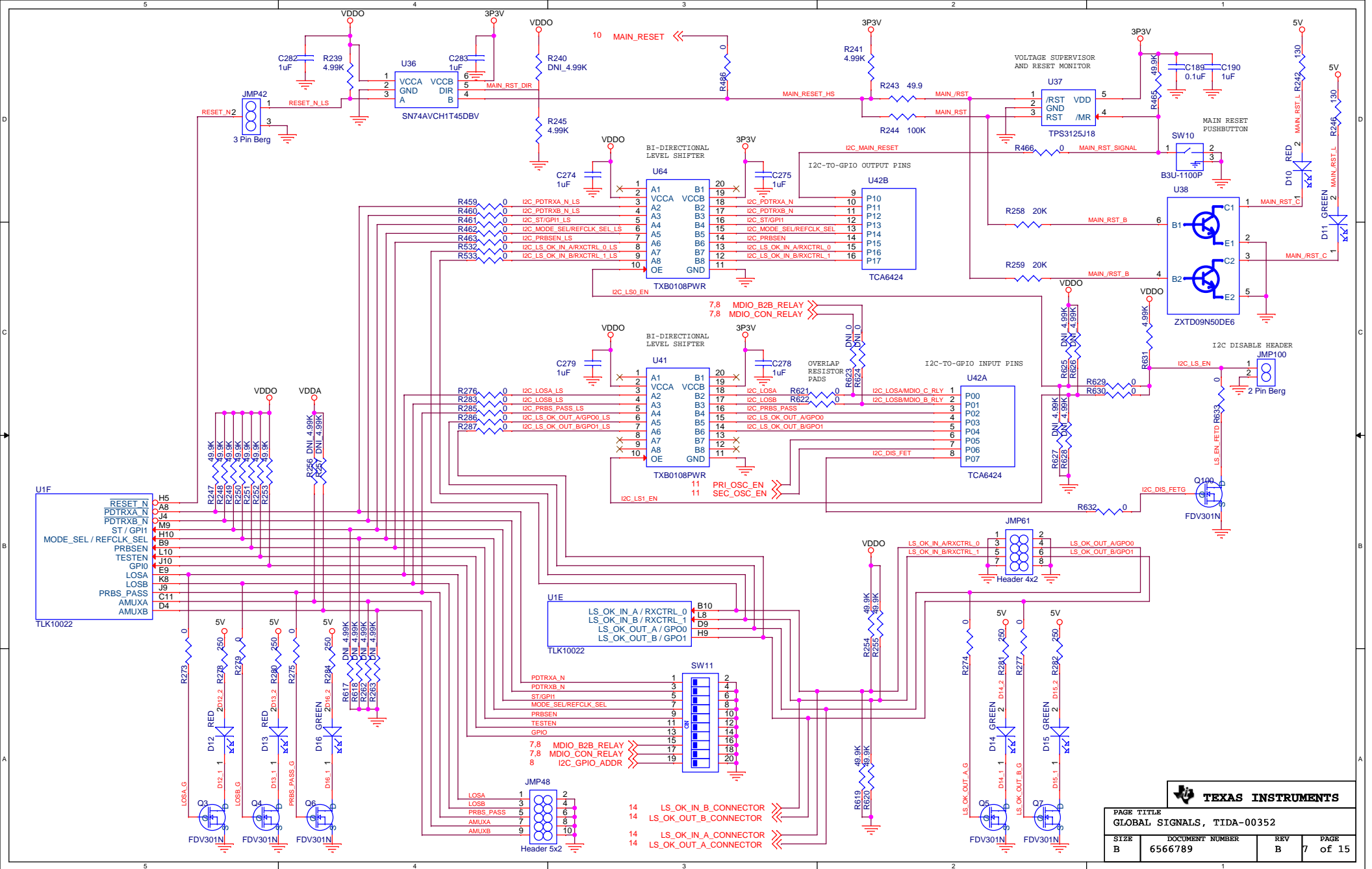


TLK10022 DEVICE POWER / LOCAL DECOUPLING



TLK10022 DEVICE GROUND

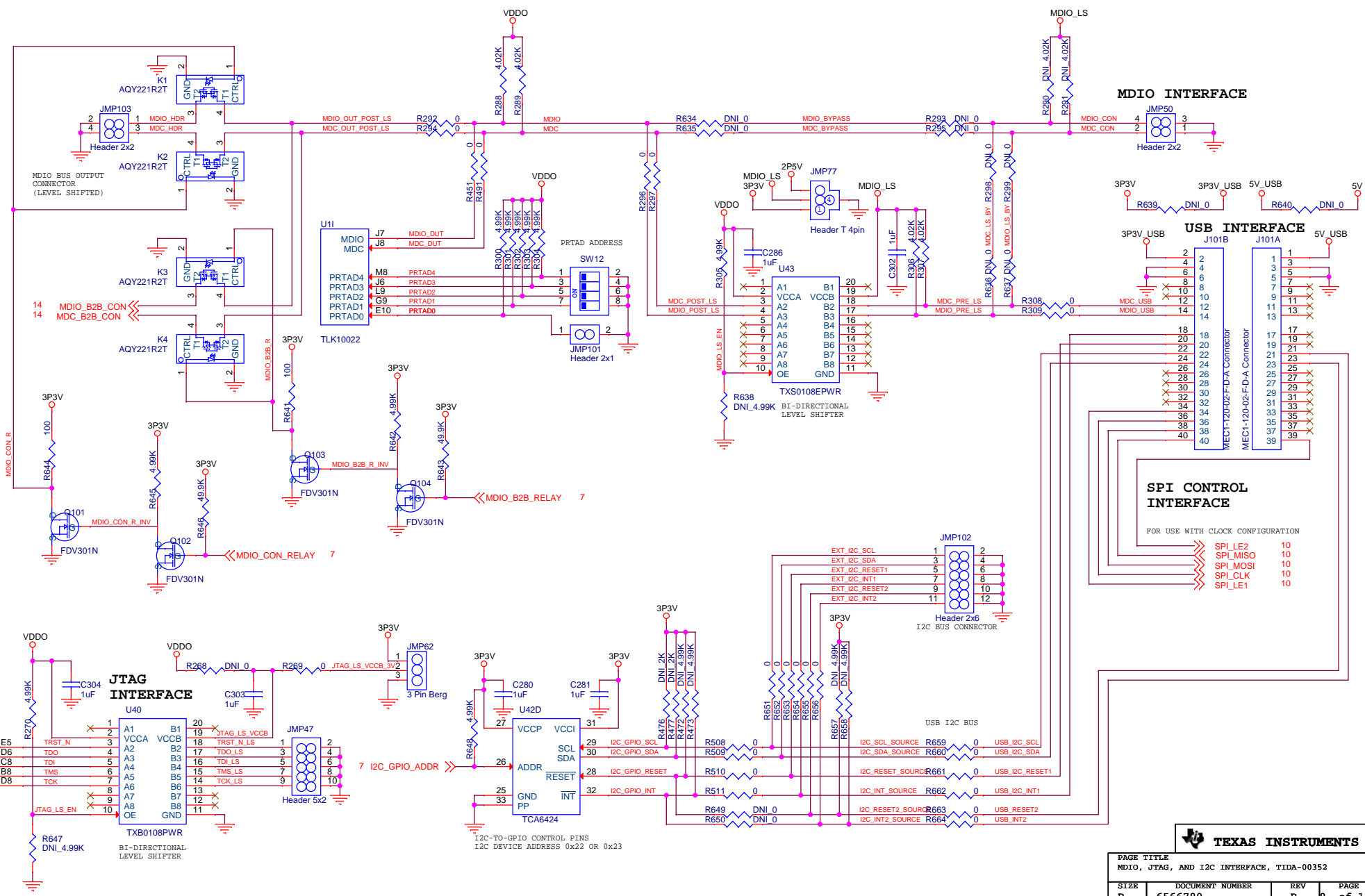




TEXAS INSTRUMENTS

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SIZE	DOCUMENT NUMBER	REV	PAGE
B	6566789	B	7 of 15

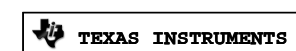


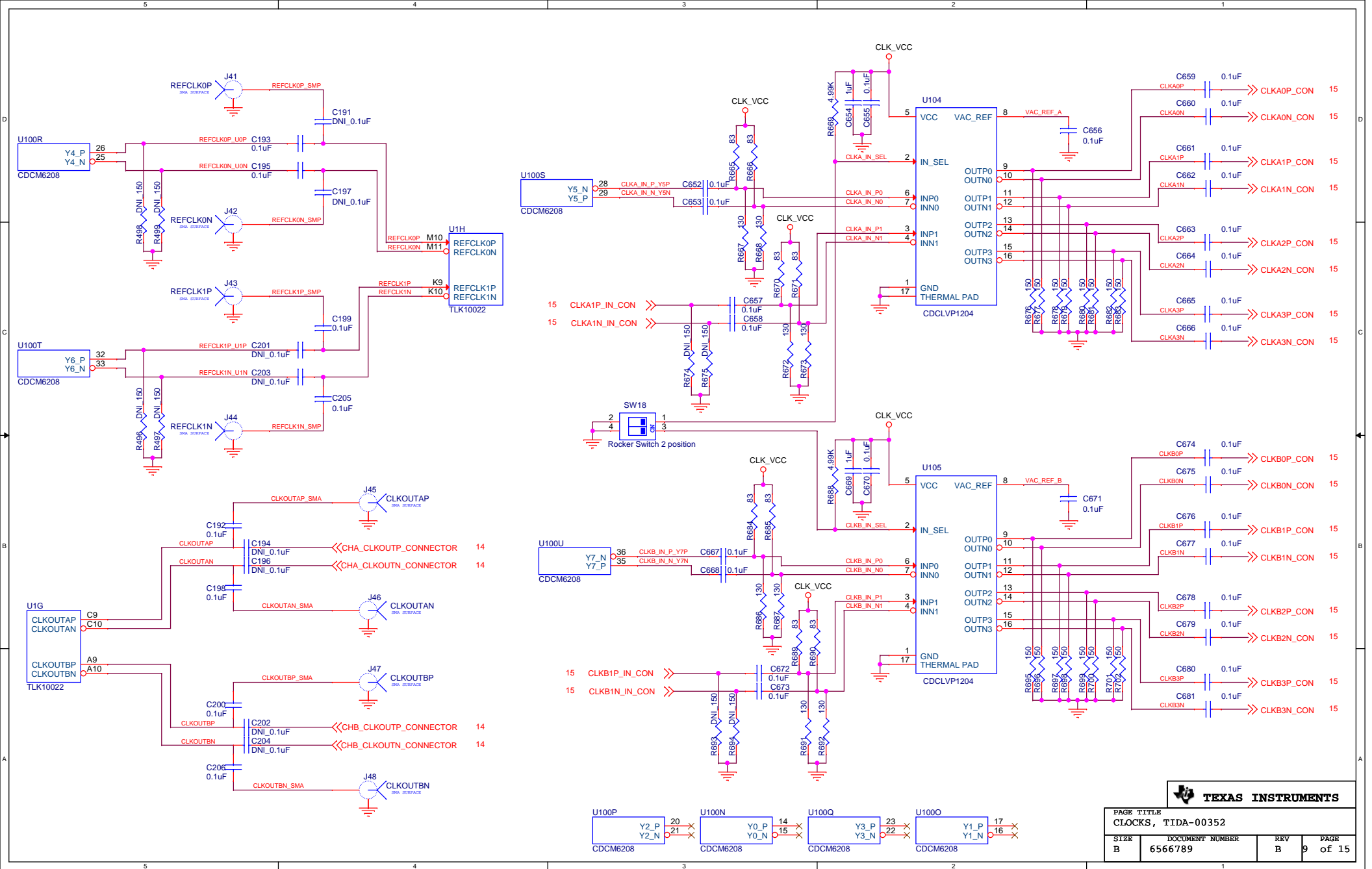
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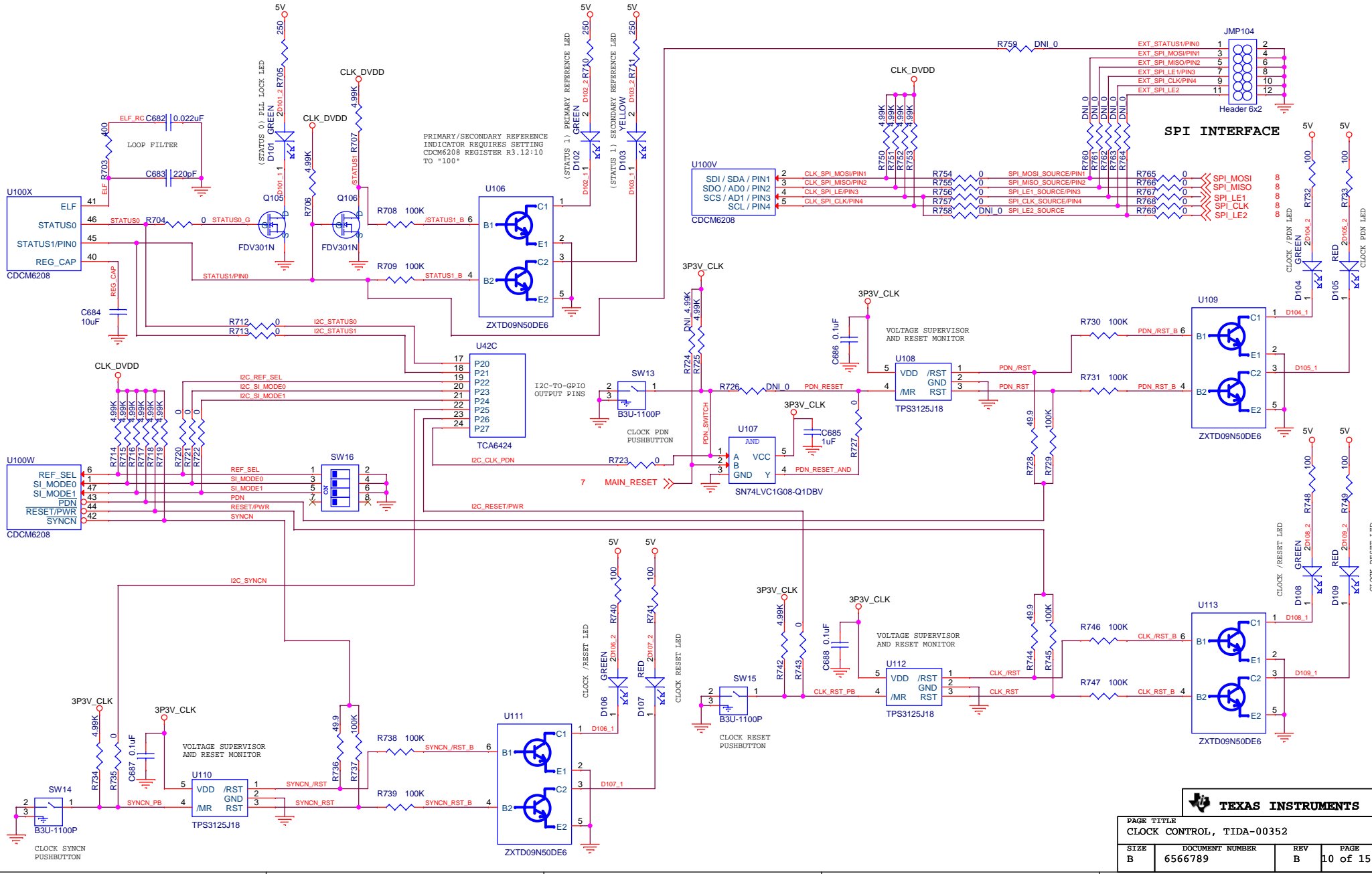
USB INTERFACE

SPI CONTROL INTERFACE

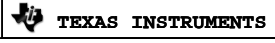
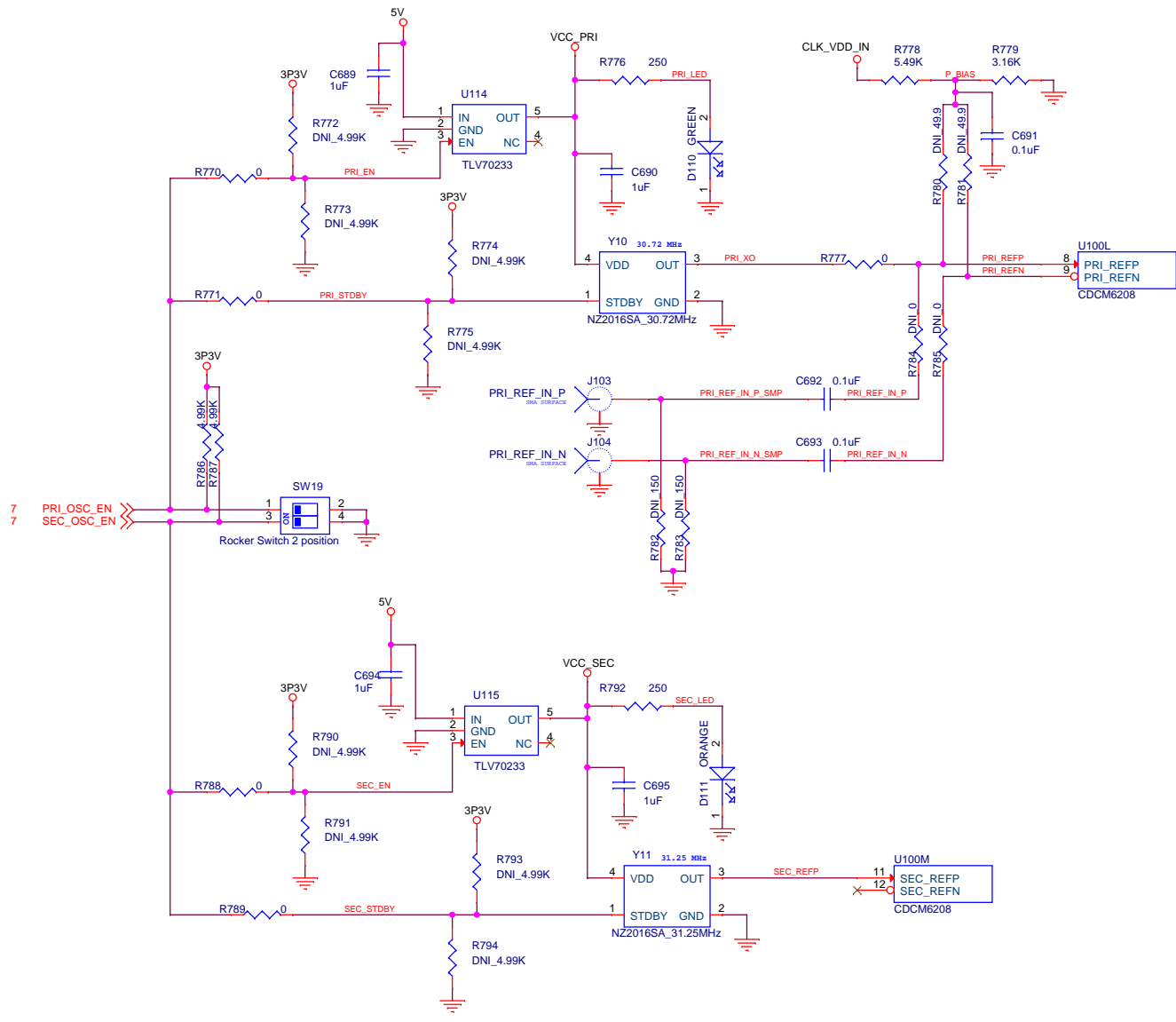
- FOR USE WITH CLOCK CONFIGURATION
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 - SPI_MISO 10
 - SPI_MOSI 10
 - SPI_CLK 10
 - SPI_LE1 10





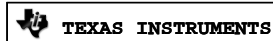


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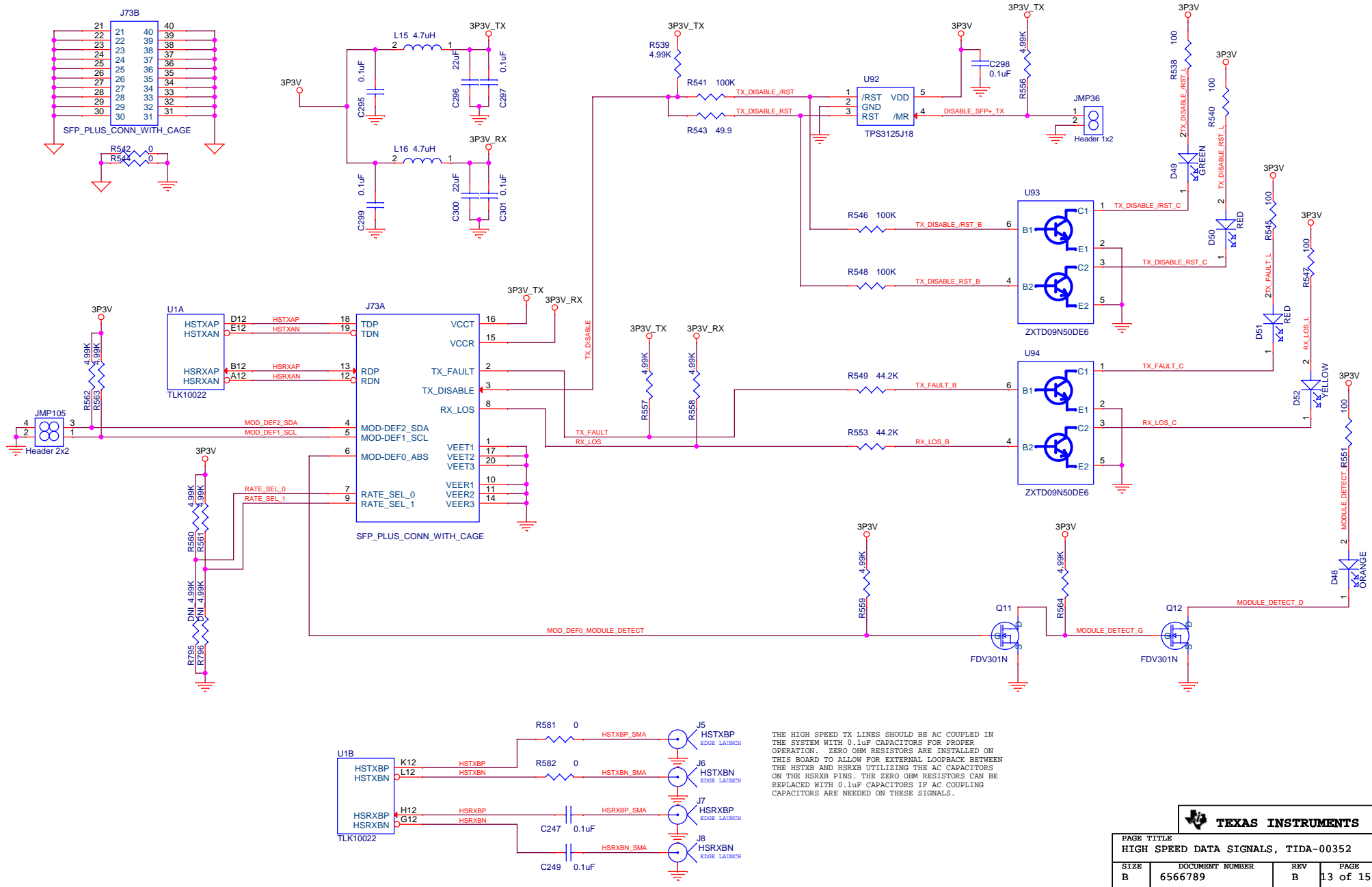


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CRYSTAL OSCILLATORS, TIDA-00352			
SIZE	DOCUMENT NUMBER	REV	PAGE
B	6566789	B	11 of 15

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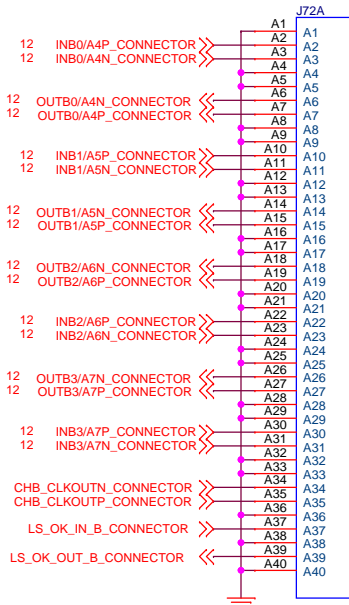
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LOW SPEED DATA SIGNALS, TIDA-00352			
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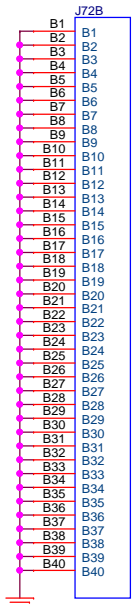
THE HIGH SPEED TX LINES SHOULD BE AC COUPLED IN THE SYSTEM WITH 0.1uF CAPACITORS FOR PROPER OPERATION. ZERO OHM RESISTORS ARE INSTALLED ON THIS BOARD TO ALLOW FOR EXTERNAL LOOPBACK BETWEEN THE HSTXB AND HSRXB UTILIZING THE AC CAPACITORS ON THE HSRXB PINS. THE ZERO OHM RESISTORS CAN BE REPLACED WITH 0.1uF CAPACITORS IF AC COUPLING CAPACITORS ARE NEEDED ON THESE SIGNALS.



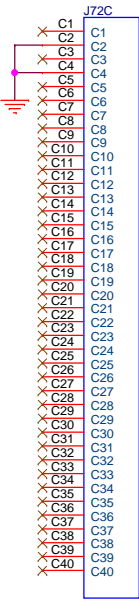
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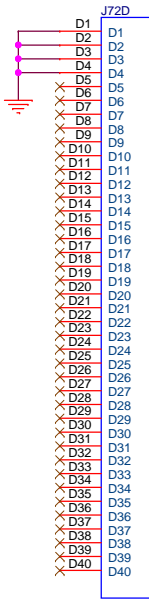
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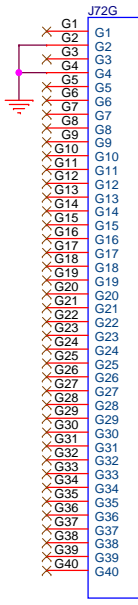
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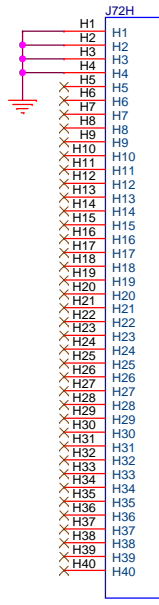
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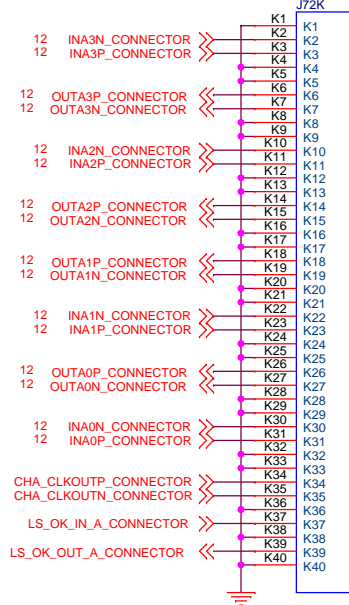
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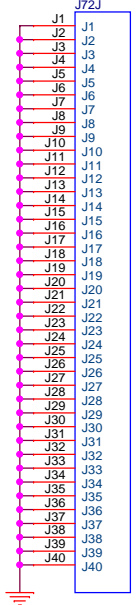
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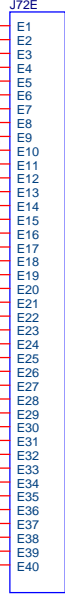
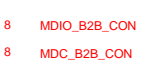
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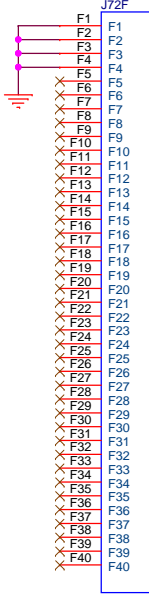
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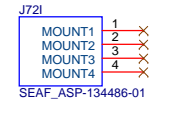
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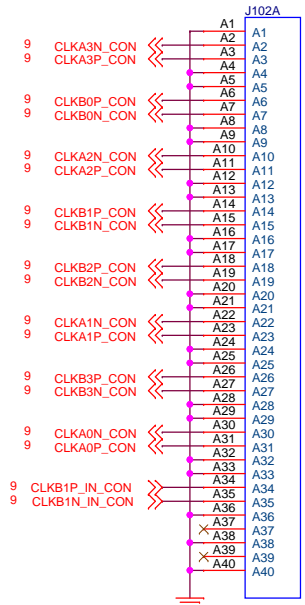
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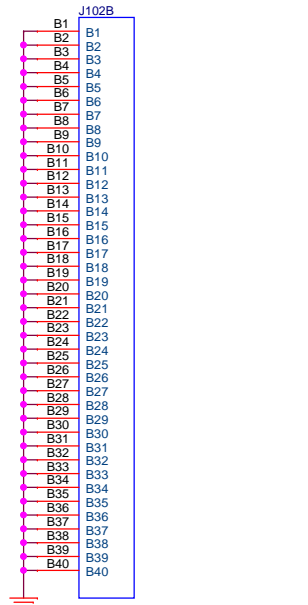
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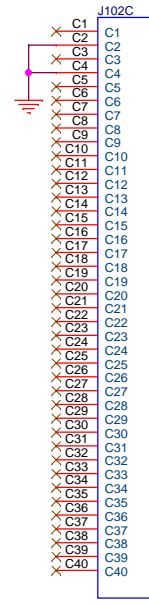
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SIZE B	DOCUMENT NUMBER 6566789	REV B	PAGE 14 of 15



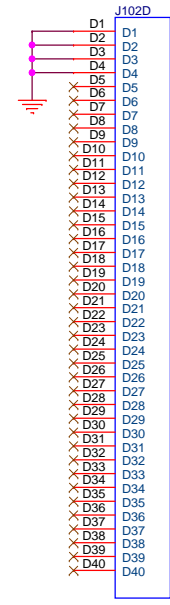
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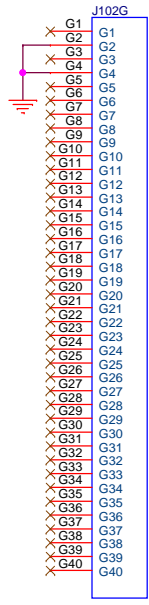
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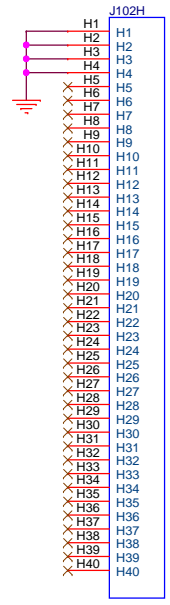
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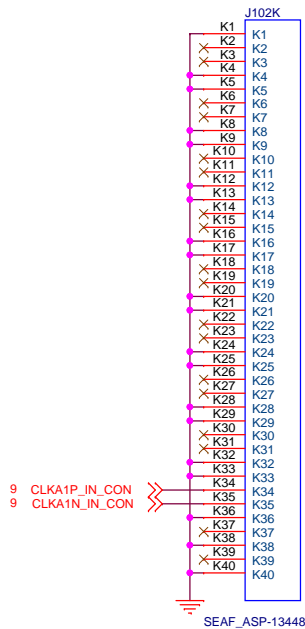
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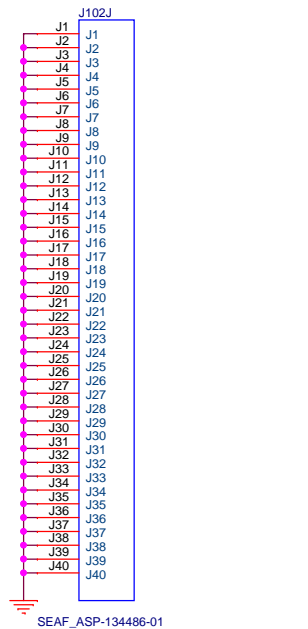
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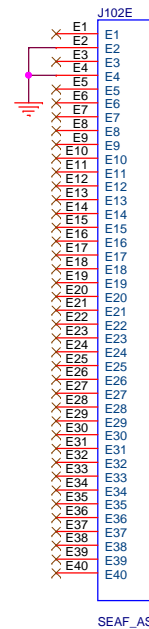
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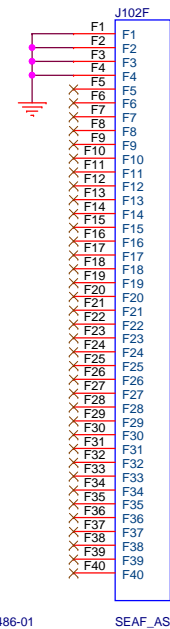
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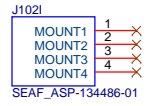
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PAGE TITLE
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SIZE B	DOCUMENT NUMBER 6566789	REV B	PAGE 15 of 15
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